

DMTH84M1SPSQ

80V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

| BV _{DSS} | Rds(on) | I _D Tc = +25°C (Note 11) |
|-------------------|---------------------------|---|
| 80V | $4m\Omega @ V_{GS} = 10V$ | 100A |

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

PowerDI5060-8

- DC-DC Converters
- Load Switch

Notes:

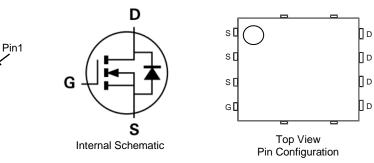


- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low RDS(ON) Minimizes On State Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH84M1SPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 🔞
- Weight: 0.097 grams (Approximate)



Ordering Information (Note 4)

Top View

| Part Number | Case | Packaging |
|-----------------|---------------|---------------------|
| DMTH84M1SPSQ-13 | PowerDI5060-8 | 2,500 / Tape & Reel |

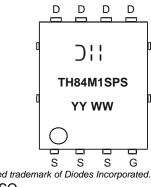
EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Bottom View

Marking Information



PowerDI is a registered trademark of Diodes Incorporated. DMTH84M1SPSQ Document number: DS42176 Rev. 2 - 2



Maximum Ratings (@Tc = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|--|--------|------------|------------------|-------|----|
| Drain-Source Voltage | | | VDSS | 80 | V |
| Gate-Source Voltage | | | V _{GSS} | ±20 | V |
| Continuous Drain Current, V _{GS} = 10V (Note 7) | D | 100 100 | A | | |
| Maximum Continuous Body Diode Forward Current (I | | ls | 83 | A | |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | Ідм | 400 | A | |
| Pulsed Body Diode Forward Current (10µs Pulse, Du | Ism | 400 | A | | |
| Avalanche Current, L = 1mH (Note 8) | | | I _{AS} | 23 | A |
| Avalanche Energy, L = 1mH (Note 8) | | | Eas | 264.5 | mJ |

Thermal Characteristics (@T_C = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--|------------------------|------------------|-------------|------|
| Total Power Dissipation (Note 5) | T _A = +25°C | PD | 1.6 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | R _{θJA} | 96 | °C/W |
| Total Power Dissipation (Note 6) | T _A = +25°C | PD | 2.8 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | RθJA | 53 | °C/W |
| Total Power Dissipation (Note 7) | Tc = +25°C | PD | 136 | W |
| Thermal Resistance, Junction to Case (Note 7) | | R _{θJC} | 1.1 | °C/W |
| Operating and Storage Temperature Range | | TJ, TSTG | -55 to +175 | °C |

Electrical Characteristics (@T_C = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|---|---------------------|-----|------|------|-------|---|
| OFF CHARACTERISTICS (Note 9) | | | | | | |
| Drain-Source Breakdown Voltage | BVDSS | 80 | — | — | V | $V_{GS} = 0V, I_D = 1mA$ |
| Zero Gate Voltage Drain Current | IDSS | | | 1 | μA | $V_{DS} = 64V, V_{GS} = 0V$ |
| Gate-Source Leakage | Igss | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ |
| ON CHARACTERISTICS (Note 9) | · | | | | | |
| Gate Threshold Voltage | Vgs(th) | 2 | — | 4 | V | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ |
| Static Drain-Source On-Resistance | Deserve | | 3.1 | 4 | mΩ | $V_{GS} = 10V, I_D = 20A$ |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 4.4 | 5.7 | 11152 | VGS = 6V, ID = 20A |
| Diode Forward Voltage | Vsd | _ | 0.8 | 1.2 | V | VGS = 0V, IS = 20A |
| DYNAMIC CHARACTERISTICS (Note 10) | · | | | | | |
| Input Capacitance | Ciss | _ | 4209 | — | | $V_{DS} = 40V, V_{GS} = 0V,$ f = 1MHz |
| Output Capacitance | Coss | | 1513 | — | pF | |
| Reverse Transfer Capacitance | Crss | _ | 62 | _ | | |
| Gate Resistance | Rg | _ | 2.2 | — | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$ |
| Total Gate Charge (V _{GS} = 6V) | Qg | | 41 | — | | V _{DS} = 40V, I _D = 20A |
| Total Gate Charge (V _{GS} = 10V) | Qg | | 63 | — | nC | |
| Gate-Source Charge | Qgs | _ | 17 | — | nc | |
| Gate-Drain Charge | Q _{gd} | _ | 16 | _ | | |
| Turn-On Delay Time | tD(ON) | _ | 16 | _ | | |
| Turn-On Rise Time | t _R | _ | 24 | _ | | $V_{DD} = 40V, V_{GS} = 10V,$ $I_D = 20A, R_G = 6\Omega$ |
| Turn-Off Delay Time | tD(OFF) | _ | 53 | — | ns | |
| Turn-Off Fall Time | tF | _ | 31 | — | | |
| Body Diode Reverse Recovery Time | t _{RR} | _ | 56 | _ | ns | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 100 | _ | nC | Is = 20A, di/dt = 100A/µs |

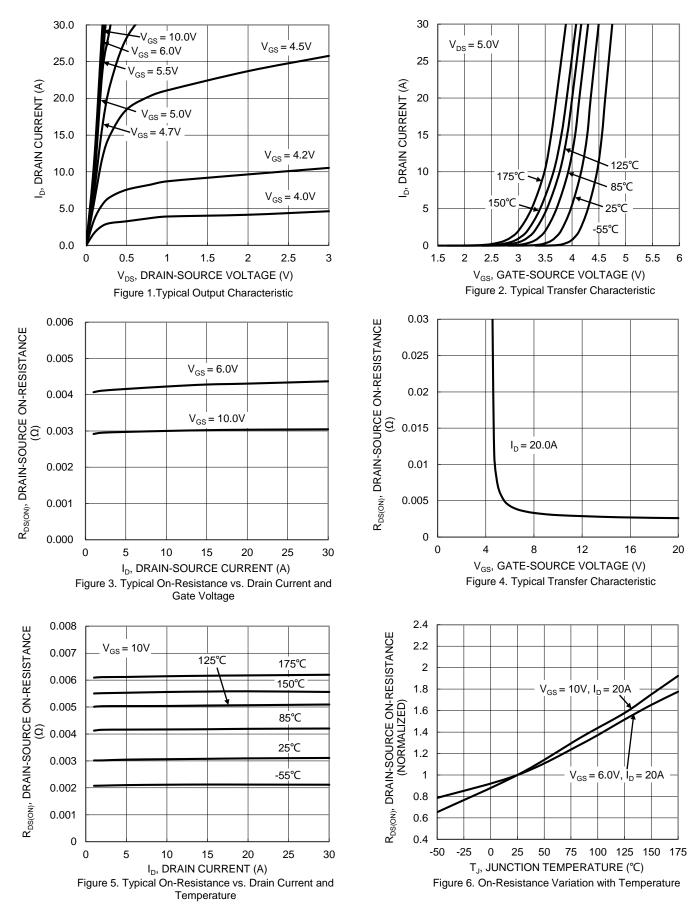
Notes:

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
Thermal resistance from junction to soldering point (on the exposed drain pad).

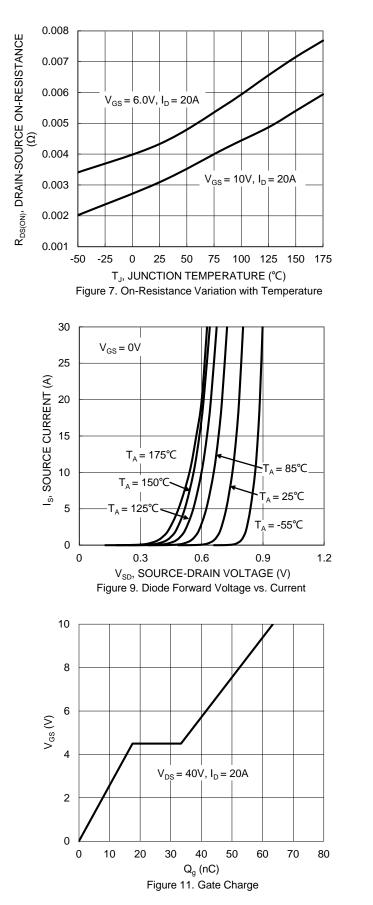
8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$. 9. Short duration pulse test used to minimize self-heating effect. 10. Guaranteed by design. Not subject to product testing. 11. Package limited.

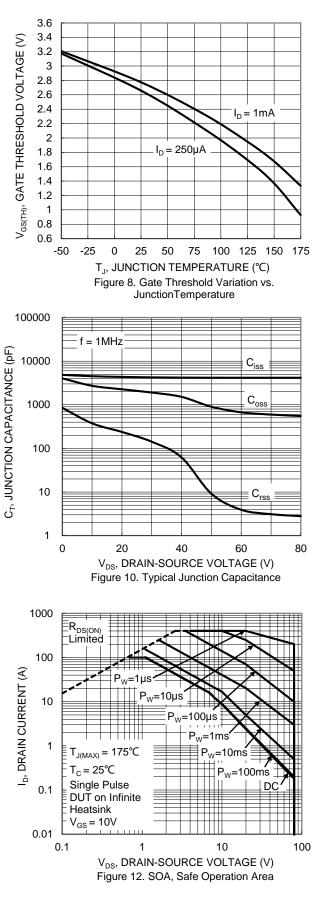


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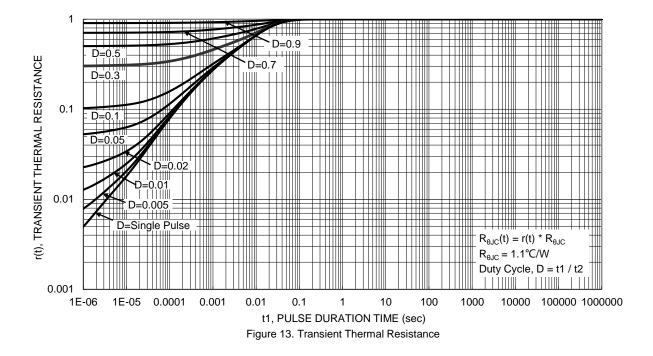






DMTH84M1SPSQ Document number: DS42176 Rev. 2 - 2



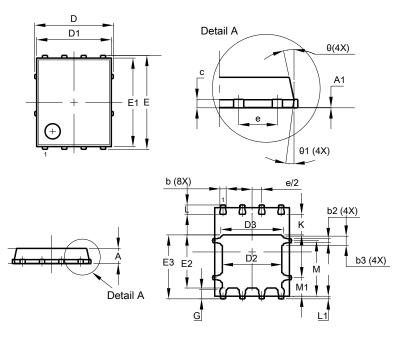




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

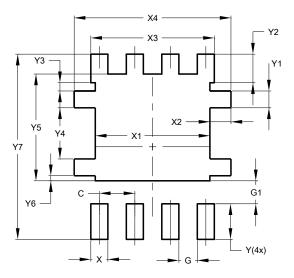


| PowerDI5060-8 | | | | | |
|---------------|----------------------|----------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 0.90 | 1.10 | 1.00 | | |
| A1 | 0.00 | 0.05 | - | | |
| b | 0.33 | 0.51 | 0.41 | | |
| b2 | 0.200 | 0.350 | 0.273 | | |
| b3 | 0.40 | 0.80 | 0.60 | | |
| С | 0.230 | 0.330 | 0.277 | | |
| D | | 5.15 BSC | ; | | |
| D1 | 4.70 | 5.10 | 4.90 | | |
| D2 | 3.70 | 4.10 | 3.90 | | |
| D3 | 3.90 | 4.30 | 4.10 | | |
| E | 6.15 BSC | | | | |
| E1 | 5.60 | 6.00 | 5.80 | | |
| E2 | 3.28 | 3.68 | 3.48 | | |
| E3 | 3.99 | 4.39 | 4.19 | | |
| е | 1.27 BSC | | | | |
| G | 0.51 | 0.71 | 0.61 | | |
| K | 0.51 | - | - | | |
| L | 0.51 | 0.71 | 0.61 | | |
| L1 | 0.100 | 0.200 | 0.175 | | |
| М | 3.235 | 4.035 | 3.635 | | |
| M1 | 1.00 | 1.40 | 1.21 | | |
| Θ | 10° | 12° | 11° | | |
| Θ1 | 6° | 8° | 7° | | |
| Al | All Dimensions in mm | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 1.270 |
| G | 0.660 |
| G1 | 0.820 |
| Х | 0.610 |
| X1 | 4.100 |
| X2 | 0.755 |
| X3 | 4.420 |
| X4 | 5.610 |
| Y | 1.270 |
| Y1 | 0.600 |
| Y2 | 1.020 |
| Y3 | 0.295 |
| Y4 | 1.825 |
| Y5 | 3.810 |
| Y6 | 0.180 |
| Y7 | 6.610 |



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